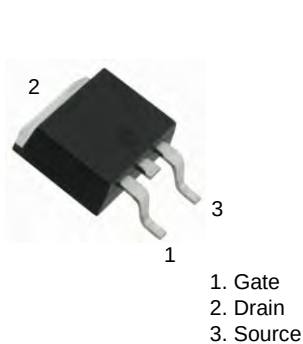
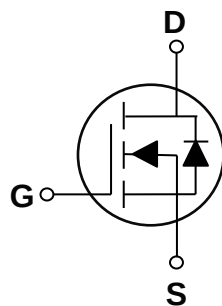


100V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO-252 Pin Configuration



BVDSS	RDS(ON)	ID
100V	9.2mΩ	60A

Features

- 100V,60A, $R_{DS(ON)} = 9.2m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	+20 / -12	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	60	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	38	A
I_{DM}	Drain Current – Pulsed ¹	240	A
EAS	Single Pulse Avalanche Energy ²	211	mJ
IAS	Single Pulse Avalanche Current ²	65	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	94	W
	Power Dissipation – Derate above 25°C	0.75	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.33	$^\circ\text{C/W}$



FTK0976D

100V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1mA$	---	0.054	---	V/ $^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=100V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=80V$, $V_{GS}=0V$, $T_J=125^{\circ}\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=+20V$, $V_{DS}=0V$	---	---	100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$, $I_D=15A$	---	7.4	9.2	m Ω
		$V_{GS}=4.5V$, $I_D=8A$	---	10.6	14	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	1.0	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.5	---	mV/ $^{\circ}\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V$, $I_D=3A$	---	11	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=50V$, $V_{GS}=10V$, $I_D=8.5A$	---	37.8	76	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	7.8	16	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	8.4	17	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=50V$, $V_{GS}=10V$, $R_G=6\Omega$ $I_D=1A$	---	14.6	30	ns
T_r	Rise Time ^{3, 4}		---	21.5	44	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	54	108	
T_f	Fall Time ^{3, 4}		---	84.3	168	
C_{iss}	Input Capacitance	$V_{DS}=50V$, $V_{GS}=0V$, $F=1MHz$	---	2250	4500	pF
C_{oss}	Output Capacitance		---	410	820	
C_{rss}	Reverse Transfer Capacitance		---	25	50	
R_g	Gate resistance	$V_{GS}=0V$, $V_{DS}=0V$, $F=1MHz$	---	1.43	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	60	A
I_{SM}	Pulsed Source Current		---	---	120	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V$, $I_S=15A$, $di/dt=100A/\mu s$ $T_J=25^{\circ}\text{C}$	---	42.4	---	nS
Q_{rr}	Reverse Recovery Charge		---	46.5	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V$, $V_{GS}=10V$, $L=0.1mH$, $I_{AS}=65A$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

100V N-Channel MOSFETs

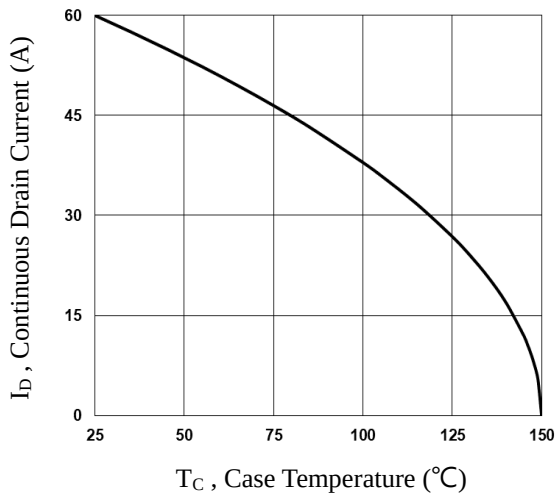


Fig.1 Continuous Drain Current vs. T_C

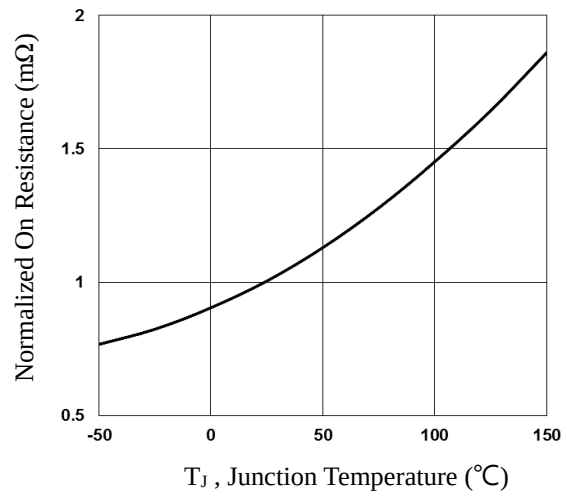


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

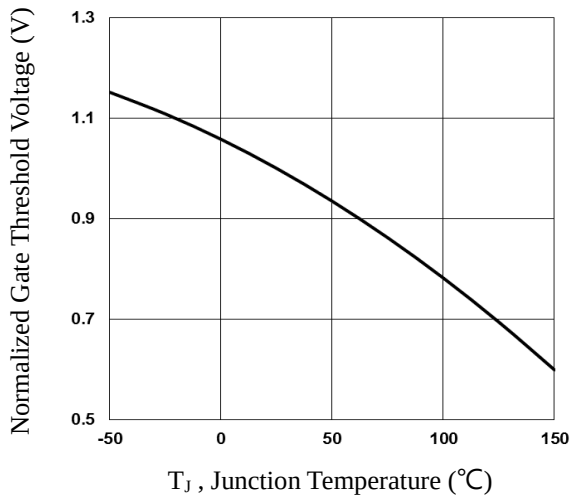


Fig.3 Normalized V_{th} vs. T_J

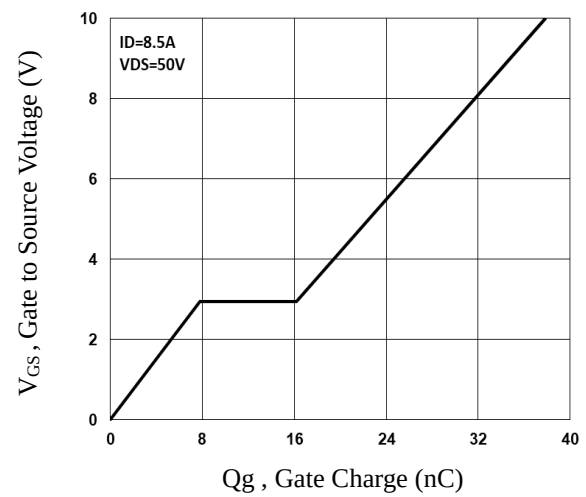


Fig.4 Gate Charge Characteristics

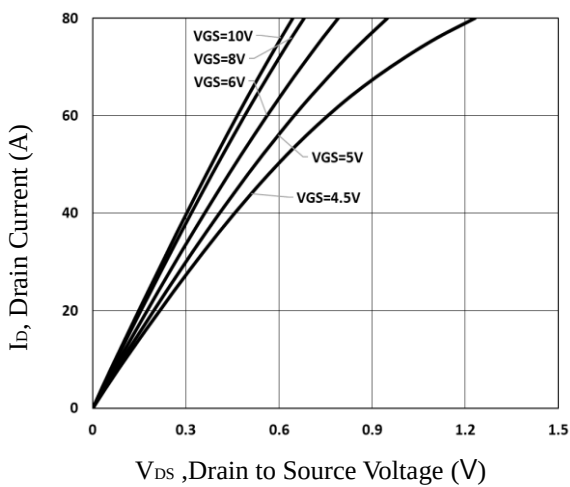


Fig.5 Typical Output Characteristics

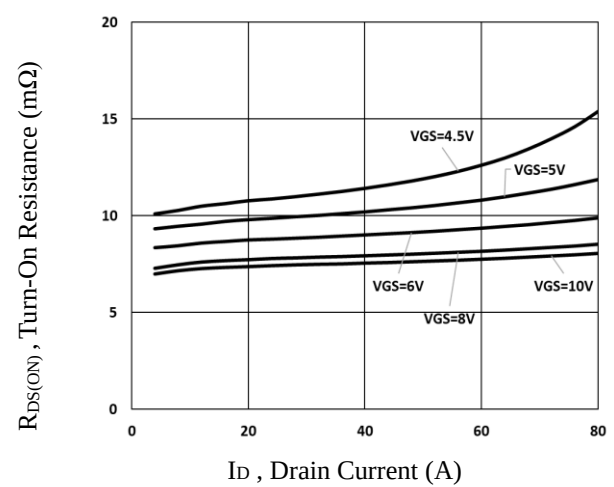
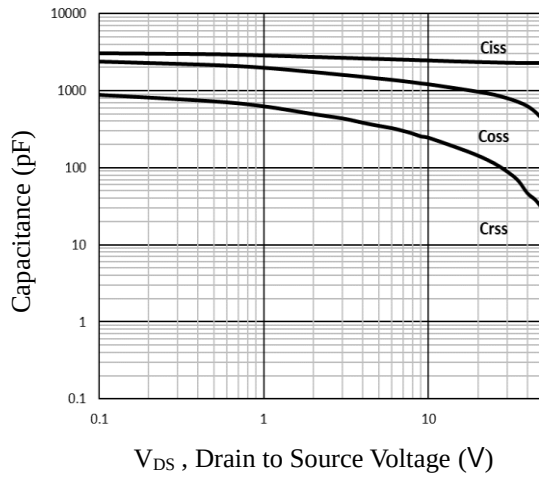
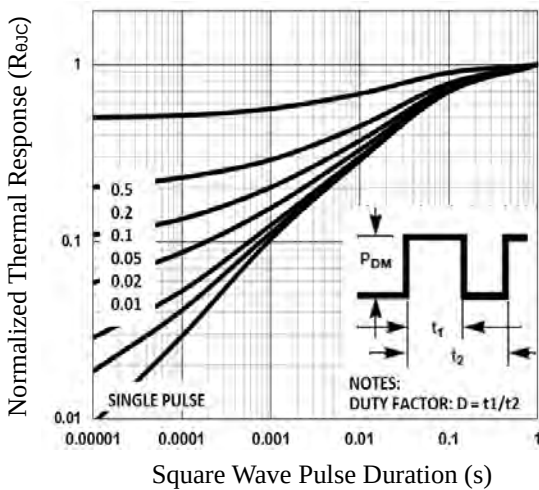
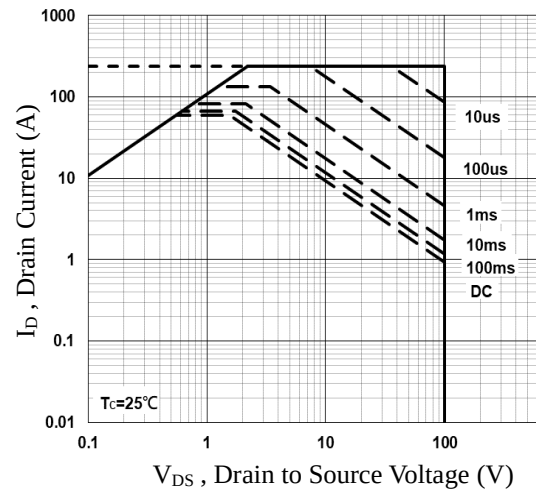
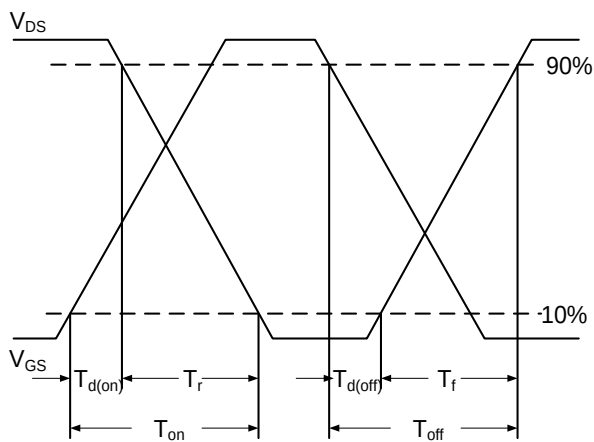
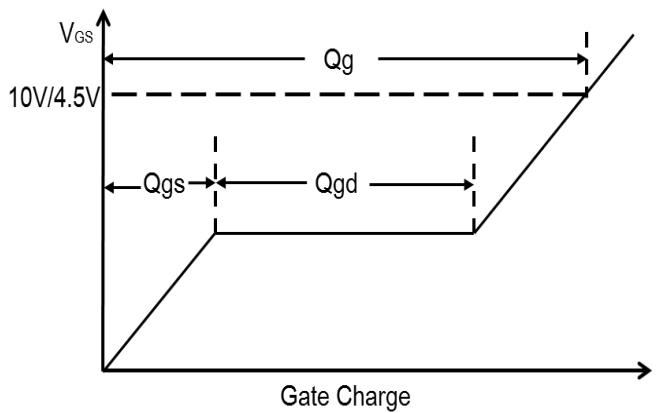


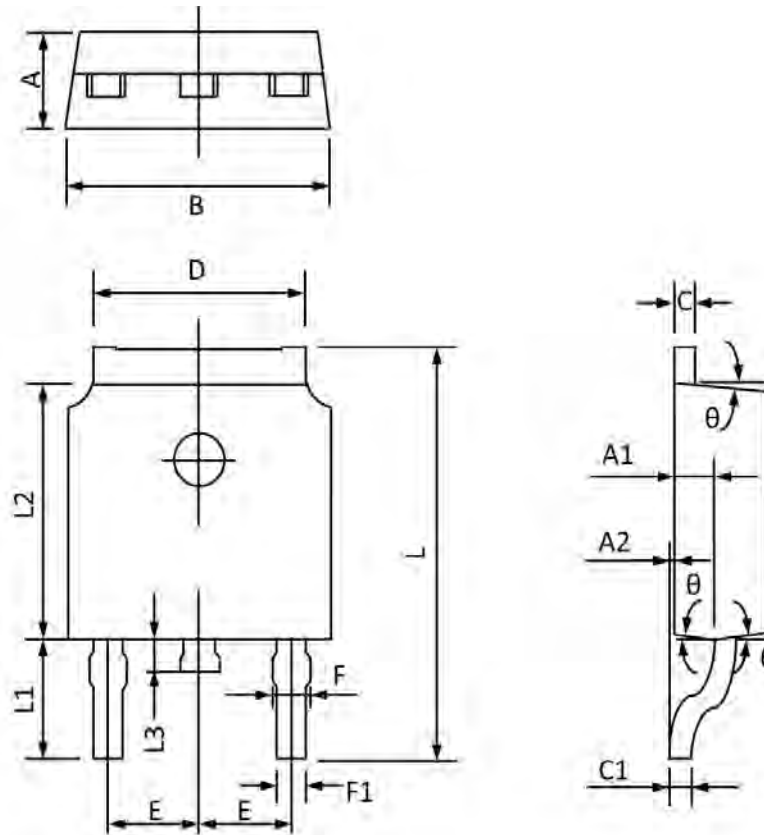
Fig.6 Turn-On Resistance vs. I_D

100V N-Channel MOSFETs



100V N-Channel MOSFETs

TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°